

ACS37002

400 kHz, High Accuracy Current Sensor

with Pin-Selectable Gains and Adjustable Overcurrent Fast Fault in SOICW-16 Package

FEATURES AND BENEFITS IDESCRIPTION

- High operating bandwidth for fast control loops or where high-speed currents are monitored \Box 400 kHz bandwidth
	- \Box 1.1 µs typical response time
- High accuracy
	- \Box 1% maximum sensitivity error over temperature (K series)
	- \Box 8 mV maximum offset voltage over temperature
	- \Box Non-ratiometric operation with V_{REF} output
	- □ Low noise LA package
	- \lozenge 160 mV_{RMS} for 3.3 V supply
	- \lozenge 124 mV_{RMS} for 5 V supply
	- \Box Differential sensing for high immunity to external magnetic fields
	- \square No magnetic hysteresis
- Adjustable fast overcurrent fault
	- \Box 1 µs typical response time
	- \Box Pin adjustable threshold
- Externally configurable gain settings using two logic pins \square Four adjustable gain levels for increased design flexibility

Continued on the next page…

PACKAGE: 16-Pin SOICW (suffix MA/LA)

Not to scale

The ACS37002 is a fully integrated Hall-effect current sensor in an SOICW-16 package that is factory-trimmed to provide high accuracy over the entire operating range without the need for customer programming. The current is sensed differentially by two Hall plates that subtract out interfering external commonmode magnetic fields.

The package construction provides high isolation by magnetically coupling the field generated by the current in the conductor to the monolithic Hall sensor IC which has no physical connection to the integrated current conductor. The MA package is optimized for higher isolation with dielectric withstand voltage, $3125 V_{RMS}$, and $0.85 \text{ m}\Omega$ conductor resistance. The LA package is optimized for lower noise with 2250 V_{RMS} dielectric withstand voltage and 1 m Ω conductor resistance.

The ACS37002 has functional features that are externally configurable and robust without the need for programming. Two logic gain selection pins can be used to configure the device to one of four defined sensitivities and corresponding current ranges. A fast overcurrent fault output provides shortcircuit detection for system protection with a fault threshold that is proportional to the current range and can be set with an analog input. The reference pin provides a stable voltage that corresponds to the 0 A output voltage. This reference voltage allows for differential measurements as well as a device-referred voltage to set the overcurrent fault threshold.

Devices are RoHS compliant and lead (Pb) free with 100% matte-tin-platted leadframes.

Figure 1: Typical Bidirectional Application Showing 00 Gain Select Configuration. For more application circuits, refer to the Application and Theory section.

FEATURES AND BENEFITS (continued)

- \Box Enabling measurement ranges from 10 to 133 A in both unidirectional and bidirectional modes
- Low internal primary conductor resistance $0.85 \text{ m}\Omega$ (MA) and $1 \text{ m}\Omega$ (LA) for better power efficiency
- UL 62368-1:2014 (ed. 2) certification, highly isolated compact SOICW-16 surface mount package (MA) \Box 3125 V_{RMS} rated dielectric withstand voltage \square 1097 $\rm V_{RMS}$ / 1550 $\rm V_{DC}$ basic insulation voltages \Box 565 V_{RMS} / 800 V_{DC} reinforced insulation voltages
- Wide operating temperature, -40° C to 150 $^{\circ}$ C
- AEC-Q100 Grade 0, automotive qualified

SELECTION GUIDE

[1] Refer to the part specific performance characteristics sections for Gain_Sel configuration.

[2] Contact Allegro for additional options.

[3] The device performance is optimized from –40°C to 125°C; however, the device can still operate to an ambient temperature of 150°C. The device shares the same qualifications as the L temperature devices unless otherwise stated.

Table of Contents

ABSOLUTE MAXIMUM RATINGS

[1] Tested on the ASEK37002 Evaluation Board (TED-0002825).

ISOLATION AND PACKAGE CHARACTERISTICS

[1] Certification pending.

MA PACKAGE SPECIFIC PERFORMANCE

^[1] Production tested for 1 second at 3125 V_{RMS} per UL 62368-1 (edition 2).
^[2] Agency type-tested at 5000 V for 1 minute per UL 62368-1 (edition 2) Section 5.4.7.

LA PACKAGE SPECIFIC PERFORMANCE

^[1] Production tested for 1 second at 2250 $\rm{V_{RMS}}$ per UL 62368-1 (edition 2).
^[2] Agency type-tested at 3600 V for 1 minute per UL 62368-1 (edition 2) Section 5.4.7.

[3] Certification pending.

PINOUT DIAGRAM AND TERMINAL LIST TABLE

Terminal List Table

Figure 3: Functional Block Diagram

COMMON ELECTRICAL CHARACTERISTICS: Valid through full operating temperature range, T_A = – 40°C to 150°C, **C_{BYPASS} = 0.1 μF, and V_{CC} = 5 V or 3.3 V, unless otherwise specified**

Continued on the next page…

COMMON PERFORMANCE CHARACTERISTICS (VIOUT): Valid through full operating temperature range, T_A = – 40°C to 150°C, C_{BYPASS} = 0.1 μF, and V_{CC} = 5 V or 3.3 V, unless otherwise specified

Continued on the next page…

COMMON PERFORMANCE CHARACTERISTICS (VREF, FAULT, GAIN_SEL): Valid through full operating temperature range, $T_A = -40^\circ$ **C to 150°C, C_{BYPASS} = 0.1 μF, and V_{CC} = 5 V or 3.3 V, unless otherwise specified**

^[1] V_{CC} rate +1 V/ms, for best accuracy.
^[2] Typical value is factory default.

[3] Guaranteed by design and bench validated

ACS37002LMABTR-050B5-M

ACS37002LMABTR-050B5-M PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and Norol individual drift distr

ACS37002LMABTR-066B5-M

ACS37002LMABTR-066B5-M PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.
[3] Lifetime drift characteristics are based on a statisti

ACS37002LMABTR-050U5-M

ACS37002LMABTR-050U5-M PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

(1) Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift dis

ACS37002LMABTR-066U5-M

ACS37002LMABTR-066U5-M PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

(1) Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift dis

ACS37002LMABTR-050B3

ACS37002LMABTR-050B3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.

ACS37002LMABTR-066B3

ACS37002LMABTR-066B3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

^[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.
^[3] Lifetime drift characteristics are based on a stat

ACS37002LMABTR-050U3

ACS37002LMABTR-050U3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

(1) Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift dis

ACS37002LMABTR-066U3

ACS37002LMABTR-066U3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

^[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.
^[3] Lifetime drift characteristics are based on a stat

ACS37002KMABTR-050B5-M

ACS37002KMABTR-050B5-M PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 125°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

^[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.
^[3] Lifetime drift characteristics are based on a stat

ACS37002KMABTR-050B3

ACS37002KMABTR-050B3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, TA = – 40°C to 125°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.

ACS37002LLAATR-015B5

ACS37002LLAATR-015B5 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

^[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.
^[3] Lifetime drift characteristics are based on a stat

ACS37002LLAATR-025B5

ACS37002LLAATR-025B5 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 5 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and Normath distribution of the

ACS37002LLAATR-015B3

ACS37002LLAATR-015B3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.

[2] Typicals values are the mean ±3 sigma statistical combination of production and AEC-Q100 individual drift distributions. These are formatted as mean ±3 sigma.

ACS37002LLAATR-025U3

ACS37002LLAATR-025U3 PERFORMANCE CHARACTERISTICS: Valid through full operating temperature range, T_A = -40°C to 150°C, C_{BYPASS} = 0.1 µF, and V_{CC} = 3.3 V, unless otherwise specified

[1] Typicals values are the mean ±3 sigma of production distributions. These are formatted as mean ±3 sigma.
[2] Typicals values are the mean ±3 sigma statistical combination of production and Normath distribution difful

FUNCTIONAL DESCRIPTION

Power-On Reset Operation

The descriptions in this section assume: temperature = 25° C, with the labeled test conditions. The provided graphs in this section show V_{IOUT} moving with V_{CC} . The voltage of V_{IOUT} during a high-impedance state will be most consistent with a known load (R_L, C_L) .

POWER-ON/POWER-OFF

As V_{CC} ramps up, the V_{IOUT} and V_{REF} outputs are high impedance until V_{CC} reaches and passes $V_{POR(H)}$ [1] in Figure 4. V_{REF} and V_{IOUT} will continue to report until V_{CC} is less than $V_{POR(I)}$ [5] in Figure 4, at which point they will go high impedance. Note that the time it takes the output to reach a steady state will depend on the external circuitry used.

POWER-ON DELAY (t_{POD})

When the supply is ramped to $V_{\text{POR(H)}}$ [2] in Figure 4, the device will require a finite time to power its internal components before the outputs are released from high impedance and can respond to an input magnetic field. Power-On Time, t_{POD} , is defined as the time it takes for the output voltage to settle within $\pm 10\%$ of its steady-state value under an applied magnetic field, which can be seen as the time from [1] to [A] in Figure 5. After this delay, the output will quickly approach $V_{\text{IOUT(IP)}} =$ Sens \times IP + V_{REF} .

Figure 5: t_{POD} , R_L = Pull-Up

Figure 4: Power States Thresholds with V_{IOUT} Behavior for a 5 V Device, R_L = Pull-Down

Allegro MicroSystems 955 Perimeter Road Manchester, NH 03103-3353 U.S.A. www.allegromicro.com

Overvoltage Detection (OVD)

To ensure that the device output is reporting accurately, the device contains an overvoltage detection flag. This flag on V_{IOUT} can be used to alert the system that the supply voltage is outside of the operational limits. When V_{CC} raises above $V_{OVD(H)}[3]$ in Figure 6, V_{IOUT} will go high impedance and be pulled by the load resistor to V_{CC} or GND. V_{REF} continues to output normally.

There is hysteresis between OVD enable and disable thresholds to reducing nuisance flagging and clears.

The enable time for OVD, t_{OVDE} , is the time from $V_{\text{OVD(H)}}[4]$ to OVD flag [B] in Figure 6. The enable flag for OVD has a counter to reduce transients faster than 64 µs from triggering nuisance flags.

The disable time for OVD, $t_{\text{OVD}(D)}$, is the time from $V_{\text{OVD}(L)}$ [5] until the device returns to normal operation [C] in Figure 6. The OVD disable time does not have a counter.

Figure 6: t_{POD} and $t_{\text{OVD(E/D)}}$ with R_L = Pull-Up

Absolute Maximum Ratings

These are the maximum application or environmental conditions that the device can be subjected before damage may occur.

SUPPLY ZENER CLAMP VOLTAGES

If the voltage applied to the device continues to increase past overvoltage detection, there is a point when the Zener diodes will turn on. These internal diodes are in place to protect the device from short high voltage or ESD events and should not be used as a feature to reduce the voltage on a line. Continued exposure to voltages higher than normal operating voltage, V_{CC} can weaken or damage the Zener diodes, which will potentially damage the part.

FORWARD AND REVERSE SUPPLY VOLTAGE

These are the largest voltage magnitudes that can be supplied to V_{CC} from GND during programing or transient switching. This voltage should not be used as a DC voltage bias for an extended time.

FORWARD AND REVERSE OUTPUT VOLTAGE

The Forward Output Voltage or V_{FIOUT} voltage can be no greater than V_{CC} + 0.5 up to 6.5 V. This is the greatest voltage that the output can be biased with from GND during programming or transient switching. The Reverse Output Voltage or V_{RIOUT} should not drop below –0.5 V during programming or transient switching. These voltages should not be used as a DC voltage bias for an extended time.

FORWARD AND REVERSE REFERENCE/FAULT VOLTAGE

The Forward Reference/Fault Voltage or V_{F-RF} voltage can be no greater than V_{CC} + 0.5 up to 6.5 V. This is the greatest voltage that the V_{REF} and V_{OCF} can be biased with from GND during programming or transient switching. The Reverse Output Voltage or V_{R-RF} should not drop below -0.5 V during programming or transient switching. These voltages should not be used as a DC voltage bias for an extended time.

OUTPUT SOURCE AND SINK CURRENT

This is the maximum current that V_{IOUT} can passively sink or source before damage may occur.

AMBIENT TEMPERATURE (TA)

This is the ambient temperature of the device. The Operating Ambient Temperature Range is the ambient temperature range that the Common Electricals and Common Performance Characteristics limits are valid. The Optimized Ambient Temperature Range is the ambient temperature range that the device-specific performance characteristics limits are valid. ACS37002L devices have optimized performance in the -40° C to 150°C ("L" temperature) range. ACS37002K devices have optimized performance in the -40° C to 125°C ("K" temperature) range. The -40° C to 125°C ("K" temperature) range devices have Device Specific Performance optimized within the –40°C to 125°C temperature range but will still operate in the –40°C to 150°C ("L" temperature) range.

DEFINITIONS OF OPERATING AND PERFORMANCE CHARACTERISTICS

Zero Current Voltage Output (V_{IOUT(Q)} QVO)

Zero Current Voltage Output or $V_{\text{IOUT}(Q)}$ (also called QVO) is defined as the voltage on the output, V_{IOUT} when zero amps are applied through I_p.

QVO Temperature Drift (V_{OF})

QVO Temperature Drift, or V_{QE} is defined as the drift of QVO from room to hot or room to cold (25°C to 125/150°C or 25°C to –40°C respectively). To improve over temperature performance the temperature drift is compensated with Allegro factory trim to remain within the limits across temperature.

Reference Voltage (V_{RFF})

There is a Voltage Reference Output, $(V_{REF}$) on the ACS37002. This output reports the zero current voltage for the output channel $V_{\text{I}\text{OUT}}$ allowing for differential measurement and a device referred supply for the VOC pin.

Reference Voltage Temperature Drift (V_{RF})

Reference Voltage Temperature Drift, or V_{RE} is defined as the drift of V_{REF} from room to hot or room to cold (25 $^{\circ}$ C to $125/150^{\circ}$ C or 25° C to -40° C respectively).

Offset Voltage (V_{OE})

Offset Voltage, or V_{OE,} is defined as the difference between QVO and V_{REF} (see Figure 7). V_{OE} includes the drift of QVO minus V_{REF} from room to hot or room to cold (25 $\rm ^{\circ}C$ to 125/150 $\rm ^{\circ}C$ or 25°C to –40°C respectively).

Figure 7: Offset (VOE) Between VIOUT and VREF

Output Saturation Voltage (V_{SAT(HIGH/LOW)})

Output Saturation Voltage, or V_{SAT} , is defined as the voltage that the V_{IOUT} does not pass as a result to an increasing magnitude of current. $V_{SAT(HIGH)}$ is the highest voltage the output can drive to while, $V_{SAT(LOW)}$ is the lowest. This can be seen in Figure 8. Note that changing the sensitivity does not change the V_{SAT} points.

OUTPUT VOLTAGE OPERATING RANGE (VOOR)

The Output Voltage Operating Range, or V_{OOR} , is the functional range for linear performance of V_{IOUT} and its related datasheet parameters. This can be seen in Figure 8. The V_{OOR} is the output region that the performance accuracy parameters are valid. It is possible for the output to report beyond these voltages until V_{SAT} , but certain parameters cannot be guaranteed. The output performance is demonstrated in Figure 8 through and beyond the V_{OOR} .

Figure 8: V_{OOR}, V_{SAT} and SENS with Full Scale

Sensitivity (Sens)

Sensitivity, or Sens, is the ratio of the output swing versus the applied current through the primary conductor, I_P . This current causes a voltage deviation away from QVO on the V_{IOUT} output until V_{SAT} . The magnitude and direction of the output voltage swing is proportional to the magnitude and direction of the applied current. This proportional relationship between output and input is Sensitivity and is defined as:

$$
Sens = \frac{V_{\text{IOUT(11)}} - V_{\text{IOUT(12)}}}{I_1 - I_2}
$$

where I_1 and I_2 are two different currents, and where $V_{\text{IOUT(II)}}$ and $V_{\text{IOUT(12)}}$ are the voltages of the device at the applied currents. V_{IOUT} , I_1 , or I_2 can be QVO with zero current.

Sensitivity Error (Esens)

Sensitivity Temperature Drift, or E_{sens}, is the drift of Sens from room to hot or room to cold (25°C to 125°C or 25°C to –40°C respectively). No trimming/programming is needed as temperature drift is compensated with Allegro factory trim.

Figure 9: Output Accuracy Pocket for Room and Across Temperature

Gain Selection Pins

The ACS37002 features external gain selection pins that configures the device sensitivity. The gain select logic is latched based on the pin voltage at startup. Either pin may be shorted directly to VCC or GND, which is logic 1 or 0 respectively. Both pins include an internal 1 MΩ pull-down resistor to GND. Externally floating pins will be interpreted as logic 0; if both pins are floating, the device will be in the 00 configuration. Specific gain select performance can be found in the selection Performance Characteristics table. To change the gain of the device, refer to Figure 18 in the Application and Theory section.

Full Scale (FS)

Full Scale, or FS, is a method to relate an input and/or output to the max input and/or output of the device. For example, 50%FS of a 10A sensor is 5A, or 50% of its maximum input current. The 50% input of 5A will cause the output to move 50%, or 50%FS. FS is used to interchangeably refer to input and output deviations when discussing input steps, fault trip thresholds and relating input to output performance. FS_{INPUT} is the input bias that results in $FS_{OLUTION}$ and these two are directly related by the device actual $\frac{601161}{201161}$ Sensitivity. Both FS input and output can be seen in Figure 8, labeled as positive or negative \overrightarrow{FS} input and \overrightarrow{FS} output. The equation for input referred FS for a 5V bidirectional device is:

$$
FS = \frac{V_{OOR(5V,Bi)}}{Sens_{Actual}} = \pm \frac{2V}{Sens_{Actual}}
$$

resultant percentage change of FS_{OUTPUT} and visa versa. Note: that a percentage change in FS_{INPIIT} is equivalent to a

Nonlinearity (E_{LIN})

 $\frac{1}{2}$ ity of the device can also change slightly. This is referred to as linearity error or F_{max} (see Figure 10). Consider two currents linearity error or E_{LIN} (see Figure 10). Consider two currents, exactual components in the contract of the contract of the process of the process change in sensitivity from one field to another. Error is calculated Separately for positive $(E_{LIN(+)})$ and negative $(E_{LIN(-)})$ currents, As the amount of field applied to the part changes, the sensitiv-
 $\frac{1}{2}$ (1) $\frac{1}{2}$ $I_1(1/2$ FS) and $I_2(FS)$. Ideally, the sensitivity of the device is the same for both fields. Linearity Error is calculated as the percent and the percent errors are defined as:
 \int Sense₁₂₊

$$
E_{\text{LIN}(\pm)} = \left(1 - \frac{\text{Sense}_{12\pm}}{\text{Sens}_{11\pm}}\right) \times 100\%
$$

$$
Sens_{IX+} = \frac{V_{IOUT(IX+)} - V_{REF}}{I_{X+}}
$$

$$
Sens_{IX-} = \frac{V_{IOUT(IX-)} - V_{REF}}{I_{X-}}
$$

I2+ = 2 × I1+

where:

Ix are positive and negative currents through $I_{\rm P}$, such that $|I_{+2}| = 2 \times |I_{+1}|$ and $|I_{-2}| = 2 \times |I_{-1}|$. $E_{LIN} = max(E_{LIN(+)}, E_{LIN(-)})$

Total Output Error (E_{TOT})

The Total Output Error is the current measurement error from the sensor IC as a percentage of the actual applied current. This is equivalent to the difference between the ideal output voltage and the actual output voltage, divided by the ideal sensitivity, relative to the current applied to the device, or simplified to:

$$
\rm E_{TOT} = \frac{V_{IOUT(ACTUAL)} - (Sens_{(IDEAL)} \times I_{PR} + V_{REF})}{(Sens_{(IDEAL)} \times I_{PR})} \times 100
$$

Total Output Error incorporates all sources of error and is a function of current. At relatively high currents, Total Output Error will be mostly due to sensitivity error, and at relatively low inputs, Total Output Error will be mostly due to Offset Voltage (V_{OF}) . At $I = 0$ A, Total Output Error approaches infinity due to the offset. An example of total error at FS can be seen in Figure 10.

Note: Total Output Error goes to infinity as the amount of applied field approaches 0 A.

Power Supply Offset Error (V_{PS})

Power Supply Offset Error or $V_{OE(PS)}$ is defined at the offset error in mV between V_{CC} and $V_{CC} \pm 10\%$ V_{CC}. For a 5 V device, this is 5 to 4.5 V and 5 to 5.5 V. For a 3.3 V device, this is 3.3 to 3 V and 3.3 to 3.6 V.

Figure 10: Accuracy Error

Offset Power Supply Rejection Ratio (PSRR_O) SensIX+ ⁼ ^VIOUT(IX+) [−] ^VREF IX+

The Offset Power Supply Rejection Ratio or $PSRR_O$ is defined as $20 \times \log$ of the ratio of the change of QVO in volts over a as 20 × log of the ratio of the change of QVO in volts over a
 ± 100 mV variable AC V_{CC} centered at 5 V reported as dB in a specified frequency range. This is an AC version of the $V_{OE(PS)}$ parameter. The equation is shown below:

I2− = 2 × I2− 2 × I2− 2 × I2−

$$
PSRR_0 = 20 \times \log \left(\frac{\Delta \text{QVO}}{\Delta V_{CC}}\right)
$$

Power Supply Sensitivity Error (E_{PS})

Power Supply Sensitivity Error, or $E_{\text{Sens(PS)}}$, is defined as the percent sensitivity error measured between V_{CC} and $V_{CC} \pm 10\%$. For e. 5.5 V doving a 5 V device, this is 5 to 4.5 V and 5 to 5.5 V. For a 3.3 V device, this is 3.3 to 3 V and 3.3 to 3.6 V.

Sensitivity Power Supply Rejection Ratio (PSRR_S)

The Sensitivity Power Supply Rejection Ratio or $PSRR_S$ is defined as $20 \times \log$ of the ratio of the % change the sensitivity over the % change in V_{CC} (±100 mV variable AC V_{CC} centered at 5 V) reported as dB in a specified frequency range. This is the AC version of the $E_{Sens(PS)}$ parameter. The equation is shown below:

$$
PSRR_S = 20 \times \log \left(\frac{\Delta\%Sens}{\Delta V_{CC}} \right)
$$

FAULT BEHAVIOR

Overcurrent Fault (OCF)

As the output swings, the Overcurrent Fault pin will trigger with an active low flag if the sensed current exceeds its comparator threshold. This is internally compared with either the factoryprogrammed thresholds or via the VOC voltage when V_{VOC} > 0.1 V. This flag trips symmetrically for the positive and negative OCF operating point.

The implementation for the OCF circuitry is accurate over temperature and does not require further temperature compensation as it is dependent on the Sens and V_{OFF} parameters that are factory-trimmed flat over temperature..

OVERCURRENT FAULT OPERATING RANGE/POINT (IOCF-OR, IOCF-OP)

Overcurrent Fault Operating Range is the functional range that the OCF thresholds can be set in terms of percentage of full-scale output swing. The Overcurrent Fault Operating Point is the specific point at which the OCF trigger will occur, and is set by either V_{VOC} or the factory default setting. The I_{OCF-OP} can be seen in Figure 11 as [9] along with the FAULT pin functionality.

OVERCURRENT FAULT HYSTERESIS (IOCF-HYST)

Overcurrent Fault Hysteresis or $I_{OCF-HYST}$ is defined as the magnitude of percent FS that must drop before a fault assertion will be cleared. This can be seen as the separation between the voltages [9] to [10] in Figure 11. Note the MASK and HOLD functionality are independent of each other. The ACS37002 comes standard with an OCF $_{\text{HYS}}$ of 120 mV (on the output) or 6%FS for a 5 V device and 9%FS for a 3.3 V device.

Figure 11: Fault Thresholds and OCF Pin Functionality

VOLTAGE OVERCURRENT PIN (VOC)

The fault trip points can be set using the VOC pin as the direct analog input for the fault trip point. The VOC pin voltage can be set using resistor dividers from V_{REF} on bidirectional devices. The fault performance is valid when V_{VOC} is within the VOC Operating Voltage Range or <0.1 V. The device will respond to voltage outside of the defined valid performance region with varied results. For a 5 V bidirectional device, setting the VOC pin to 0.5 V selects the minimum trip point, $I_{FAULT(min)}$, and setting the pin to 2 V selects the maximum trip point, $I_{FAULT(max)}$ as defined by selection performance tables. All voltages between 0.5 to 2 V for 5 V option and 0.33 to 1.321 V for 3.3 V option can linearly select a trip point between the minimum and maximum levels, as shown in Figure 12. When V_{OC} < 0.1 V, the internal EEPROM fault level will be used.

The resulting equation for the fault is:

$$
OCF_{\%FS} [\%] = \frac{V_{OC(V_{CC})}[V]}{V_{OC(V_{CC})100\%}[V]} \times 100 [\%]
$$

$$
I_{OCF} [A] = OCF_{\%FS} [\%] \times I_{PR} [A]
$$

Table 1: V_{OC(Vcc)} thresholds and corresponding percentage of the Full-Scale **Output for Bidirectional and Unidirectional operational modes**

Figure 12: VOC Functional Range

400 kHz, High Accuracy Current Sensor ACS37002 with Pin-Selectable Gains and Adjustable Overcurrent Fast Fault in SOICW-16 Package AND KHZ High Accuracy Current Sen

10

OVERCURRENT FAULT ERROR (E_{OCF})

Fault Error or E_{OCF} is the error between the $I_{OCF-OP(actual)}$ and I_{OCF-OP}(ideal).

OVERCURRENT FAULT RESPONSE TIME (t_{OCF})

the input reaches the operating point [9] (seen in Figure 13) until the OCF pin falls below $V_{FAULT-ON}$ [G]. If the OCF Mask is disabled, then t_{OCF} is equal to t_{OCF-R} seen as the time from [9] until $[F]$. Overcurrent Response Time or t_{OCF} is defined as the time from

OVERCURRENT FAULT REACTION TIME (t_{OCF-R})

the OCF pin reaches V_{OCF-ON} at point [F] with the OCF mask disable. This is the time required for the device to recognize and clear the current input rising above I_{OCF-OP} at point [9] in Figure 13 until Overcurrent Reaction Time or t_{OCF-R} is defined as the time from the fault, seen as the time between [10] until [I].

OVERCURRENT FAULT MASK TIME (tOCF-MASK)

 t_{max} time (seen in Figure 13 FF) additional amount of time the OCF must be present beyond the Overcurrent Fault Mask Time or $t_{\text{OCF-MASK}}$ is defined as the nuisance tripping of the FAULT pin. If an OCF occurs, but does t_{OCF-R} time (seen in Figure 13 [F] until [G]). This is to reduce
muisones tripping of the EAULT pin Jf on OCE easing but does not persist beyond t_{OCF-R} + $t_{OCF-MASK}$, it is not reported by the device (seen in Figure 14). This prevents short transient spikes from causing erroneous OCF flagging. Factory default setting is $t_{OCF-MASK} = 0 \,\mu s.$

are independent of each other IOCF-OP((Disable) **Figure 13: General Fault Timing. Note: the MASK and HOLD functionality**

E OVERCURRENT FAULT HOLD TIME (t_{OCF-HOLD})

Overcurrent Fault Hold Time or $t_{OCF-HOLD}$ is defined as the minimum time OCF flag will be asserted after a sufficient OCF event. After the hold time has been reached, the OCF will release if the OCF condition has ended (seen in Figure 13 [G] until [J]) or persist if the OCF condition is still present (seen in Figure 15 [G] until [J]). Factory default is 0 ms.

ERSIST Amps **OVERCURRENT FAULT PERSIST**

The ACS37002 has a fault persist option that will maintain the a POR ever OCF flag if a flag occurred until a POR event.

OCF DISABLE

The ACS37002 has the ability to disable overcurrent fault function- μ , the OCF pin will fel. ality; when this is disabled, the OCF pin will remain in high Z.

Figure 14: Fault Condition Clearing Before Mask Time Is Reached

Figure 15: Fault Hold with Clear Fault After Hold Time

RESPONSE CHARACTERISTICS DEFINITIONS AND PERFORMANCE DATA

Response Time (tRESPONSE)

The time interval between a) when the sensed input current reaches 90% of its final value, and b) when the sensor output reaches 90% of its full-scale value.

Propagation Delay (t_{pd})

The time interval between a) when the sensed input current reaches 20% of its full-scale value, and b) when the sensor output reaches 20% of its full-scale value.

Rise Time (t_r)

The time interval between a) when the sensor reaches 10% of its full-scale value, and b) when it reaches 90% of its full-scale value.

Output Slew Rate (SR)

The rate of change $[V/\mu s]$ in the output voltage from a) when the sensor reaches 10% of its full-scale value, and b) when it reaches 90% of its full-scale value.

Response Time, Propagation Delay, Rise Time, and Output Slew Rate

Temperature Compensation

To help compensate for the effects temperature has on performance, the ACS37002 has an integrated internal temperature sensor. This sensor and compensation algorithms help to standardize device performance over the full range of optimized temperatures. This allows for room temperature system calibration and validation of end-of-line modules.

Temperature Compensation Update Rate

There is an 8 ms update time that is required to maintain a valid temperature compensated output; that is, temperature compensations are calculated and applied every 8 ms.

APPLICATION AND THEORY

Application Circuits

Figure 16: Applications Circuits for GAIN_SEL, VOC, and FAULT pin

These configurations are simplified to the network required for functionality. Bypass and load capacitors are recommend for best performance.

Theory and Functionality – VOC and OCF

Figure 17: OCF Signal Path Simplified and Detailed Blocks of Functionality

VOC DRIVEN BY NON-INVERTING BUFFERED VREF

If the VOC pin is being driven by a non-inverted buffered V_{REF} , it is important to consider that any error from the $\rm V_{REF}$ pin will be gained as well. For instance, if V_{REF} error is +10 mV and the $gain = 4$ for the non-inverting operational amplifier, then the VOC pin will be 40 mV from the expected target. For unidirectional devices, OCF would be subjected to an additional 4% error due to the error propagation from V_{REF} through the gain stage.

POWER SUPPLY DECOUPLING CAPACITOR AND OUTPUT CAPACITIVE LOADS

The higher the capacitive load on the outputs (V_{REF} , V_{IOUT}), the larger the decoupling capacitor should be on the power supply (V_{CC}) to maintain performance.

Dynamically Change Gain in a System

The ACS37002 has GAIN_SEL pins that are used to change the gain of the device on startup. If a more dynamic gain is desired, then reduce V_{CC} below $V_{POR(L)}$ and restart the device by returning V_{CC} to the nominal voltage with the new desired GAIN_SEL configuration. The GAIN_SEL pin voltage must greater than the

desired configuration voltage ($V_{H(SEL)}$ or $V_{L(SEL)}$) at or before V_{CC} > $V_{POR(H)}$ in order to successfully change the device gain. The GAIN_SEL pin voltage is latched at startup, and any changes to the pin voltages after the devices V_{IOUT} comes out of high Z will not affect gain. The cycle time to complete this operation is up to $2 \times t_{\text{POD}}$.

Figure 18: GAIN_SEL Dynamic Gain Changing Timing Diagram

THERMAL PERFORMANCE

Thermal Rise vs. Primary Current

Self-heating due to the flow of current should be considered during the design of any current sensing system. The sensor, printed circuit board (PCB), and contacts to the PCB will generate heat as current moves through the system.

The thermal response is highly dependent on PCB layout, copper thickness, cooling techniques, and the profile of the injected current. The current profile includes peak current, current "on-time", and duty cycle. While the data presented in this section was collected with direct current (DC), these numbers may be used to approximate thermal response for both AC signals and current pulses.

The plot in Figure 19 shows the measured rise in steady-state die temperature of the ACS37002 versus continuous current at an ambient temperature, T_A , of 25 °C. The thermal offset curves may be directly applied to other values of T_A . Conversely, Figure 20 shows the maximum continuous current at a given T_A . Surges beyond the maximum current listed in Figure 21 are allowed given the maximum junction temperature, $T_{J(MAX)}$ (165°C), is not exceeded.

Figure 19: Self heating in the MA and LA package due to current flow

Figure 20: Maximum Continuous Current at a Given T_A

The thermal capacity of the ACS37002 should be verified by the end user and is specific to the application. The maximum junction temperature, $T_{J(MAX)}$ (165°C), should not be exceeded. Further information on this application testing is available in the DC and Transient Current Capability application note on the Allegro website ([http://www.allegromicro.com/en/Design-Center/](http://www.allegromicro.com/en/Design-Center/Technical-Documents/Hall-Effect-Sensor-IC-Publications/DC-and-Transient-Current-Capability-Fuse-Characteristics.aspx) [Technical-Documents/Hall-Effect-Sensor-IC-Publications/DC](http://www.allegromicro.com/en/Design-Center/Technical-Documents/Hall-Effect-Sensor-IC-Publications/DC-and-Transient-Current-Capability-Fuse-Characteristics.aspx)[and-Transient-Current-Capability-Fuse-Characteristics.aspx\)](http://www.allegromicro.com/en/Design-Center/Technical-Documents/Hall-Effect-Sensor-IC-Publications/DC-and-Transient-Current-Capability-Fuse-Characteristics.aspx).

Evaluation Board Layout

Thermal data shown in Figure 19 and Figure 20 was collected using the ASEK37002 Evaluation Board (TED-0002825). This board includes 750 mm2 of 4 oz. copper (0.1388 mm) connected to pins 1 through 4, and to pins 5 through 8, with thermal vias connecting the layers. Top and bottom layers of the PCB are shown below in Figure 21.

Figure 21: Top and Bottom Layers for ASEK37002 Evaluation Board

Gerber files for the ASEK37002 evaluation board are available for download from the Allegro website. See the technical documents section of the ACS37002 webpage ([https://www.allegromi](https://www.allegromicro.com/en/products/sense/current-sensor-ics/zero-to-fifty-amp-integrated-conductor-sensor-ics/acs37002)[cro.com/en/products/sense/current-sensor-ics/zero-to-fifty-amp](https://www.allegromicro.com/en/products/sense/current-sensor-ics/zero-to-fifty-amp-integrated-conductor-sensor-ics/acs37002)[integrated-conductor-sensor-ics/acs37002\)](https://www.allegromicro.com/en/products/sense/current-sensor-ics/zero-to-fifty-amp-integrated-conductor-sensor-ics/acs37002).

Figure 22: Package MA, 16-Pin SOICW

